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February 1994 Revised May 2005

### 74LCX16245

# Low Voltage 16-Bit Bidirectional Transceiver with 5V Tolerant Inputs and Outputs

### **General Description**

The LCX16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is designed for low voltage (2.5V or 3.3V) V $_{\rm CC}$  applications with capability of interfacing to a 5V signal environment. The device is byte controlled. Each byte has separate control inputs which could be shorted together for full 16-bit operation. The  $T/\overline{R}$  inputs determine the direction of data flow through the device. The  $\overline{\rm OE}$  inputs disable both the A and B ports by placing them in a high impedance state.

The LCX16245 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

### **Features**

- 5V tolerant inputs and outputs
- 2.3V-3.6V V<sub>CC</sub> specifications provided
- $\blacksquare~4.5~\text{ns}~t_{PD}~\text{max}~(\text{V}_{CC}=3.3\text{V}),~20~\mu\text{A}~\text{I}_{CC}~\text{max}$
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ±24 mA output drive (V<sub>CC</sub> = 3.0V)
- Uses patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V Machine model > 200V

 Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

Note 1: To ensure the high-impedance state during power up or down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

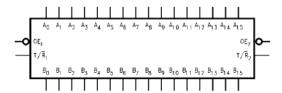
### Ordering Code:

Order Number	Package Number	Package Description
74LCX16245G (Note 2)(Note 3)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74LCX16245MEA (Note 3)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LCX16245MTD (Note 3)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: Ordering code "G" indicates Trays.

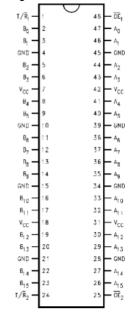
Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

### Logic Symbol

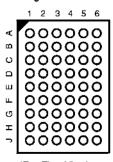


### **Connection Diagrams**

### Pin Assignment for SSOP and TSSOP



### Pin Assignment for FBGA



(Top Thru View)

### **Pin Descriptions**

Pin Names	Description
ŌĒn	Output Enable Input
T/R <sub>n</sub>	Transmit/Receive Input
A <sub>0</sub> -A <sub>15</sub> B <sub>0</sub> -B <sub>15</sub>	Side A Inputs or 3-STATE Outputs
B <sub>0</sub> -B <sub>15</sub>	Side B Inputs or 3-STATE Outputs
NC 13	No Connect

### **FBGA Pin Assignments**

		1	2	3	4	5	6
	Α	B <sub>0</sub>	NC	T/R <sub>1</sub>	ŌE <sub>1</sub>	NC	A <sub>0</sub>
	В	B <sub>2</sub>	B <sub>1</sub>	NC	NC	A <sub>1</sub>	A <sub>2</sub>
I	С	B <sub>4</sub>	B <sub>3</sub>	V <sub>CC</sub>	V <sub>CC</sub>	A <sub>3</sub>	A <sub>4</sub>
Ī	D	B <sub>6</sub>	B <sub>5</sub>	GND	GND	A <sub>5</sub>	A <sub>6</sub>
I	Е	B <sub>8</sub>	B <sub>7</sub>	GND	GND	A <sub>7</sub>	A <sub>8</sub>
I	F	B <sub>10</sub>	B <sub>9</sub>	GND	GND	A <sub>9</sub>	A <sub>10</sub>
I	G	B <sub>12</sub>	B <sub>11</sub>	V <sub>CC</sub>	V <sub>CC</sub>	A <sub>11</sub>	A <sub>12</sub>
I	Н	B <sub>14</sub>	B <sub>13</sub>	NC	NC	A <sub>13</sub>	A <sub>14</sub>
	J	B <sub>15</sub>	NC	T/R <sub>2</sub>	OE <sub>2</sub>	NC	A <sub>15</sub>

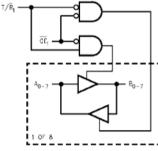
### **Truth Tables**

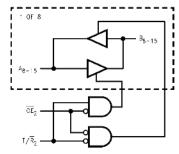
In	outs	0.1.1
OE <sub>1</sub>	T/R <sub>1</sub>	Outputs
L	L	Bus B <sub>0</sub> –B <sub>7</sub> Data to Bus A <sub>0</sub> –A <sub>7</sub>
L	Н	Bus A <sub>0</sub> -A <sub>7</sub> Data to Bus B <sub>0</sub> -B <sub>7</sub>
Н	X	HIGH Z State on A <sub>0</sub> –A <sub>7</sub> , B <sub>0</sub> –B <sub>7</sub>

Inputs		0	
OE <sub>2</sub> T/R <sub>2</sub>		Outputs	
L	L	Bus B <sub>8</sub> -B <sub>15</sub> Data to Bus A <sub>8</sub> -A <sub>15</sub>	
L	Н	Bus A <sub>8</sub> –A <sub>15</sub> Data to Bus B <sub>8</sub> –B <sub>15</sub>	
Н	X	HIGH Z State on A <sub>8</sub> -A <sub>15</sub> , B <sub>8</sub> -B <sub>15</sub>	

H = HIGH Voltage Level

### **Logic Diagrams**





Note: Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

L = LOW Voltage Level

X = Immaterial Z = High Impedance

#### Absolute Maximum Ratings(Note 4) Units Symbol Parameter Value Conditions -0.5 to +7.0 V Supply Voltage $V_{CC}$ ٧ DC Input Voltage -0.5 to +7.0 VI Vo DC Output Voltage Output in 3-STATE -0.5 to +7.0 Output in HIGH or LOW State (Note 5) -0.5 to $V_{CC} + 0.5$ DC Input Diode Current -50 V<sub>I</sub> < GND mΑ $I_{IK}$ DC Output Diode Current -50 V<sub>O</sub> < GND lok mΑ +50 Vo > Vcc ±50 DC Output Source/Sink Current mΑ lο ±100 Icc DC Supply Current per Supply Pin mΑ DC Ground Current per Ground Pin ±100 mΑ $I_{GND}$ Storage Temperature -65 to +150 °С $T_{STG}$

### Recommended Operating Conditions (Note 6)

Symbol	Parameter			Max	Units
V <sub>CC</sub>	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	v
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	Vcc	V
		3-STATE	0	5.5	·
I <sub>OH</sub> /I <sub>OL</sub>	Output Current	$V_{CC} = 3.0V - 3.6V$		±24	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±12	mΑ
		$V_{CC} = 2.3V - 2.7V$		±8	
T <sub>A</sub>	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V		0	10	ns/V

Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 5: In Absolute Maximum Rating must be observed.

Note 6: Unused inputs or I/O's must be held HIGH or LOW. They may not float.

### **DC Electrical Characteristics**

Symbol	Parameter	Conditions	V <sub>cc</sub>	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		Units
•	i didilictor	Conditions	(V)	Min	Max	Ullits
V <sub>IH</sub>	HIGH Level Input Voltage		2.3 – 2.7	1.7		v
			2.7 – 3.6	2.0		ľ
V <sub>IL</sub>	LOW Level Input Voltage		2.3 – 2.7		0.7	v
			2.7 – 3.6		0.8	ľ
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100 μA	2.3 – 3.6	V <sub>CC</sub> - 0.2		
		$I_{OH} = -8 \text{ mA}$	2.3	1.8		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2		V
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 – 3.6		0.2	
		$I_{OL} = 8mA$	2.3		0.6	
		$I_{OL} = 12 \text{ mA}$	2.7		0.4	V
		$I_{OL} = 16 \text{ mA}$	3.0		0.4	
		$I_{OL} = 24 \text{ mA}$	3.0		0.55	
I <sub>I</sub>	Input Leakage Current	0 ≤ V <sub>1</sub> ≤ 5.5V	2.3 – 3.6		±5.0	μА
loz	3-STATE I/O Leakage	0 ≤ V <sub>O</sub> ≤ 5.5V	2.3 – 3.6		±5.0	μА
		$V_I = V_{IH}$ or $V_{IL}$				μ
I <sub>OFF</sub>	Power-Off Leakage Current	$V_1$ or $V_0 = 5.5V$	0		10	μА

### DC Electrical Characteristics (Continued)

Symbol	Symbol Parameter	Conditions	V <sub>cc</sub>	T <sub>A</sub> = -40°	C to +85°C	Units
' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '		Conditions	(V)	Min	Max	Omics
Icc	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3-3.6		20	uА
		3.6V ≤ V <sub>I</sub> , V <sub>O</sub> ≤ 5.5V (Note 7)	2.3-3.6		±20	μΛ
Δl <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	$V_{IH} = V_{CC} - 0.6V$	2.3-3.6		500	μΑ

Note 7: Outputs disabled or 3-STATE only.

### **AC Electrical Characteristics**

		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, R_L = 500\Omega$						
Symbol	Parameter	V <sub>CC</sub> = 3.3	= 3.3V ± 0.3V V <sub>C</sub>		2.7V	$V_{CC} = 2.5V \pm 0.2V$		Units
Symbol	raiametei	C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		Units
		Min	Max	Min	Max	Min	Max	1
t <sub>PHL</sub>	Propagation Delay	1.5	4.5	1.5	5.2	1.5	5.4	
t <sub>PLH</sub>	A <sub>n</sub> to B <sub>n</sub> or B <sub>n</sub> to A <sub>n</sub>	1.5	4.5	1.5	5.2	1.5	5.4	ns
t <sub>PZL</sub>	Output Enable Time	1.5	6.5	1.5	7.2	1.5	8.5	ns
t <sub>PZH</sub>		1.5	6.5	1.5	7.2	1.5	8.5	ns
t <sub>PLZ</sub>	Output Disable Time	1.5	6.4	1.5	6.9	1.5	7.7	ns
t <sub>PHZ</sub>		1.5	6.4	1.5	6.9	1.5	7.7	115
t <sub>oshL</sub>	Output to Output Skew		1.0					ns
toslh	(Note 8)		1.0					115

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

### **Dynamic Switching Characteristics**

Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	T <sub>A</sub> = 25°C Typical	Units
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V	3.3	0.8	1/
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.6	v
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.8	1/
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.6	v

### Capacitance

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = Open, $V_I$ = 0V or $V_{CC}$	7	pF
C <sub>I/O</sub>	Input/Output Capacitance	$V_{CC} = 3.3V$ , $V_I = 0V$ or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CC} = 3.3V, V_{I} = 0V \text{ or } V_{CC}, f = 10 \text{ MHz}$	20	pF

### AC LOADING and WAVEFORMS Generic for LCX Family

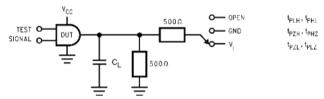
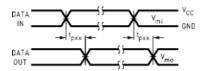
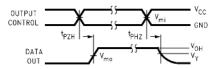


FIGURE 1. AC Test Circuit (C1 includes probe and jig capacitance)

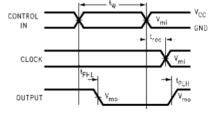
Test	Switch
t <sub>PLH</sub> , t <sub>PHL</sub>	Open
t <sub>PZL</sub> , t <sub>PLZ</sub>	$V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t <sub>PZH</sub> ,t <sub>PHZ</sub>	GND



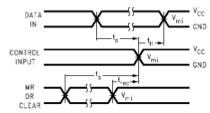
Waveform for Inverting and Non-Inverting Functions



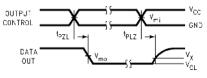
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and trec Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

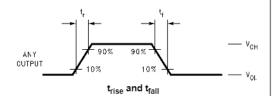
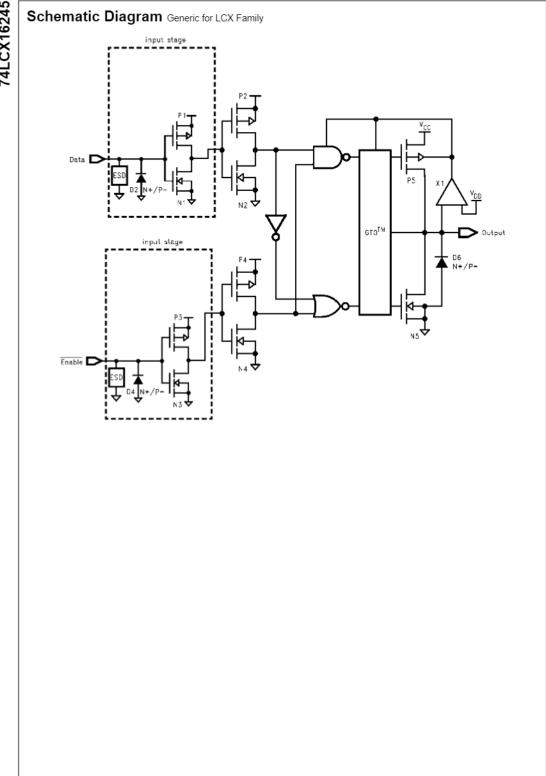
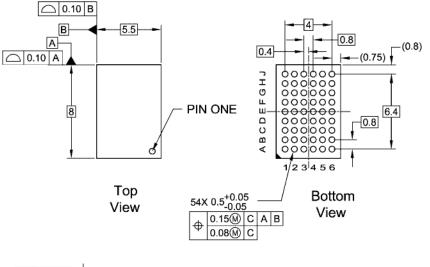


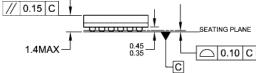
FIGURE 2. Waveforms (Input Characteristics; f =1MHz,  $t_{\rm f}$  =  $t_{\rm f}$  = 3ns)

Symbol	V <sub>CC</sub>		
	3.3V ± 0.3V	2.7V	2.5V ± 0.2V
V <sub>mi</sub>	1.5V	1.5V	V <sub>CC</sub> /2
V <sub>mo</sub>	1.5V	1.5V	V <sub>CC</sub> /2
V <sub>X</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.15V
V <sub>v</sub>	V <sub>OH</sub> = 0.3V	V <sub>OH</sub> - 0.3V	V <sub>OH</sub> - 0.15V



### Physical Dimensions inches (millimeters) unless otherwise noted



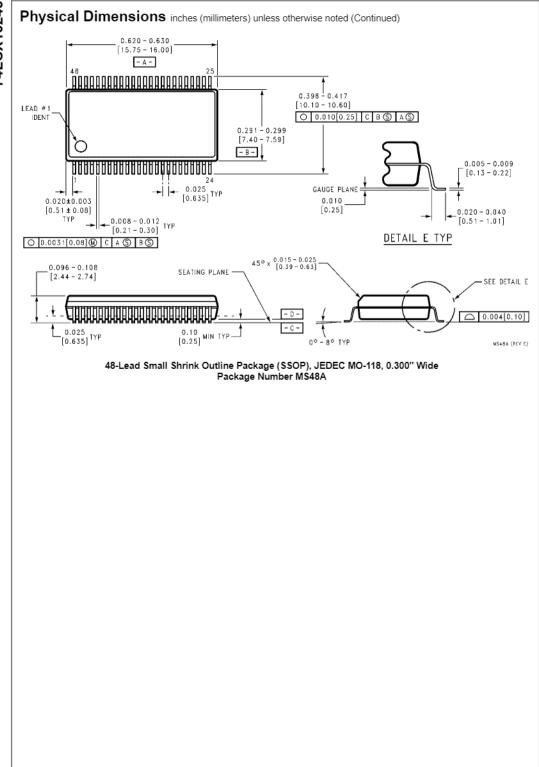


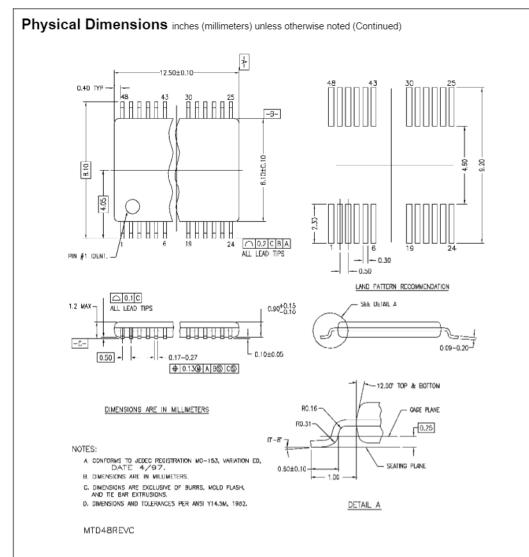
### NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
  .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
  D. DRAWING CONFORMS TO ASME Y14.5M-1994

### BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A





48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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